

Technical Datasheet

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ADESIVER RE MS

Single-component silane adhesive for resilient floors and resilient coatings installation



Description

ADESIVER RE MS is a single-component moisture curing adhesive based on silanic termination prepolymers (MS technology). The adhesive is suitable for bonding rigid LVT, SPC and LVT to wall and floor also suitable for laying all types of resilient coatings (PVC rolls). Suitable for bonding on properly prepared, absorbent and non-absorbent surfaces and on systems with radiant floor and wall heating and cooling. EC1 PLUS CERTIFICATE.

Characteristics

Mixture ratio	single-component
Application temperature	+10°C ÷ +30°C
Application	notched trowel N° 1-3
Maximum open time	1 h ⁽¹⁾
Hardening	24-36 h ⁽¹⁾
Coverage	300 - 450 g/m² depending on the subfloor.
Colour	ivory
Storage stability	12 months ⁽²⁾
Packaging	5 Kg - 10 Kg
Tool cleaning	DILUENTE ACETONE - DILUENTE DMC 50 (before the hardening of the adhesive)

1 at 20°C and 65% R.H.

2 in original sealed containers at temperatures between +10°C and +25°C

Laying conditions

Subfloor

dry, clean, planar and no-dust creating. It must be free of paints, waxes, oils or products that may impair the adhesion of the adhesive.

Humidity of subfloor

2,0% max with cement subfloors.

1,7% max with radiant floor heating cement subfloors.

0,5% max with anhydrite subfloors.

0,2% max with radiant floor heating anhydrite subfloors.

How to use

Apply ADESIVER RE MS in the required amount according to the type of support and the type of material to be glued, using the appropriate toothed spatula.

On poorly absorbent or not-absorbent substrates, remove and clean the surface from dust, grit, glue and waxes residue. Apply by cloth the adhesion promoter DILUENTE APA (see technical data sheet).

In case of installation of large-format sheets or plates on non-absorbent substrates, apply the minimum amount of adhesive

useful to ensure proper coverage of the back of the coating and always ensure the presence of an appropriate level of environmental humidity (>50% but not more than specified by the floor manufacturer). Wait 10-15 minutes after applying the adhesive before starting to install the covering or floor.

Install while the adhesive layer is still fresh: the adhesive must be pressed by rolling the coating evenly to ensure a good passage of the adhesive on the back.

Open time can change depending on temperature, relative humidity and absorption of the substrate. The times will be shorter with higher temperatures and higher levels of humidity; the times will lengthen with low temperatures, lower humidity levels and poorly/non-absorbent substrates.

In the case of use of already open packages, remove any skin formed, which conserves the remaining product and proceed to a new application.

Ensure good ventilation during application and drying of the adhesive.

Note:

Always remove from the packaging the coatings to be glued a few hours before laying in order to unload the tensions and acclimatize them to the environmental conditions. If the floor is not perfectly planar use weights (such as sand bags, adhesive packages, etc.) on the deformed parts. Use the weights at the joints and heads of the deformed coating until ADESIVER RE MS hardens (24-36 hours). Do not lay on substrates not isolated from any rise in humidity.

Warnings

The substrate should have a temperature of at least 12 - 15° C. Do not apply the adhesive if in the working environment the relative humidity exceeds 75%. Never dilute the adhesive. It releases very small amounts of methyl alcohol during curing.

Label elements

For more information about the safe use of the product it is recommended to consult the latest version of the Safety Data Sheet.

These information are given from the best of our knowledge and technical experience. They are of general character and not binding in any way our company. Every single case should be put to a practical test by the user who assumes the full responsibility of the final result of his work.